

Littelfuse, Inc.
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May 6, 2021

PCN1094

Detailed Description of Change

IXYS Integrated Circuits Division (ICD), now part of Littelfuse, has made specification changes to the Moisture Sensitivity and Soldering Profile segments contained within the Manufacturing Information section presented in the data sheets of the following devices:

CPC1317P	CPC1317PTR
CPC1335P	CPC1335PTR
LAA110PL	LAA110PLTR
LAA120PL	LAA120PLTR
LAA125PL	LAA125PLTR
LAA127P	LAA127PTR
LAA127PL	LAA127PLTR
LBA110PL	LBA110PLTR
LBA127P	LBA127PTR
LBB127P	LBB127PTR
PAA110PL	PAA110PLTR
PAA127P	PAA127PTR
PAA140P	PAA140PTR
PAA150P	PAA150PTR
PBB150P	PBB150PTR

The Moisture Sensitivity Level (MSL) classification of the 8-pin SOIC (Flatpack) package has been changed from MSL 1 to MSL 3. In addition to the MSL classification change, the Classification Temperature (maximum body temperature) of this package has been reduced from 260°C to 245°C.

These changes are effective immediately and are documented in the recent revision of the product's data sheets which are available online at www.ixysic.com.

The PCN number assigned to this action is **PCN1094** and should be referenced in any correspondence related to the change.

Reason for Change

We have discovered a small percentage of SOIC-8 devices developed package cracking issues during lead-free soldering reflow processes. To assure these devices maintain IXYS Integrated Circuits Division quality standards it was necessary to change the MSL classification and reduce the maximum (peak) body temperature limit.

Additional factory preparation as a result of the MSL 3 classification change (bake, dry pack and seal) of these devices will protect the device package from moisture ingress while in transit and during storage. This pre-shipping treatment in conjunction with the lower maximum allowed body temperature during the lead-free soldering reflow procedure will reduce package stress during reflow.

Not only will this ensure the reliability of the devices through the PCB assembly process, it will maintain the reliability of the product over its expected lifetime.

Anticipated Impact on Quality and Reliability

This change will improve the quality and reliability of the product received by the customer and throughout their PCB assembly manufacturing process.

Contact Information

For any questions related to this PCN notice, please contact Littelfuse, IXYS Integrated Circuits Division's Customer Service Department as indicated below

Customer Service Department
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now part of Littelfuse
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<https://www.ixysic.com/home/pages.nsf/req.cs>